

HCT-900 Hand Held Convection Tool

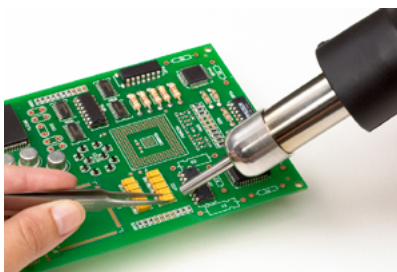
SMT Component Rework



A Versatile Hot Air Tool for SMT Soldering and De-soldering

The Metcal HCT-900 Hand Held Convection Tool offers a low cost versatile rework solution for a wide variety of production and rework application challenges.

- Closed-loop thermocouple feedback control delivers repeatable heating based on the setting programmed regardless of airflow control.
- Settings can be replicated for applications.
- Unique low noise air pump design delivers precise airflow control for the most demanding applications.
- Power off cool down functions retains airflow while unit powers down for safe operation.
- Analogue controls for heat and airflow (individually adjustable).



Applications:

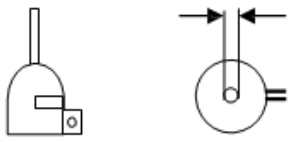
- SMT removal for QFP's, PLCC's, SOP's & TSOP devices
- Convection soldering of packages to PCB
- Heating & reflow for rework touch up
- Heat shrink & other local heating applications

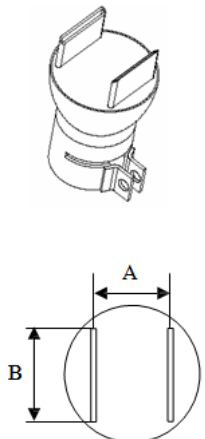
| Specifications | | | |
|--|---------------------------------|------------|------------|
| Model | HCT-900-11 | HCT-900-21 | HCT-900-10 |
| Input Voltage | 115 VAC | 230 VAC | 100 VAC |
| Power | 320 W | | |
| Pollution Degree Category | II | | |
| Storage Temperature | 0°C—60°C (32°F—140°F) | | |
| Air Pump Type | Diaphragm | | |
| Air Flow | 5-20 l/min. | | |
| Control Temperature (indication only – not calibrated) | 100°C—500°C (212°F—932°F) | | |
| Surface Resistivity | Unit: 105Ω - 106Ω. | | |
| | Hand-piece & tube: 107Ω - 1011Ω | | |
| Noise Level | Less than 46 dBA | | |
| Dimensions | 210 (L) x 170 (W) x 140 (H) mm | | |
| Weight | 4.7 kg. (10.4 lbs.) | | |
| Certification / Approvals | cTUVus, CE | | |

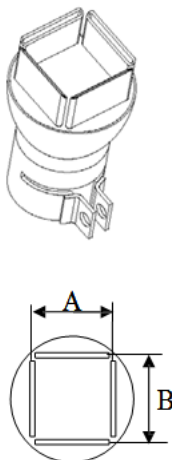


HCT-900 Ordering Information and Nozzles

HCT features a common heater design that accepts many industry standard nozzles.

| Outline: General Purpose Nozzles | Part Number | Dimension (mm) |
|---|-------------|----------------|
|  | H-D25 | 2.5 |
| | H-D50 | 5 |
| | H-D120 | 12 |

| Outline: Nozzles for SO & TSOP Packages | Part Number | Chip Package | Dimension A | Dimension B |
|--|-------------|----------------------|-------------|-------------|
|  | H-S16 | SOIC 14, 16 | 6.8 | 10.2 |
| | H-SL16 | SOL 14, 16 | 10.6 | 10.8 |
| | H-SL20 | SOL 20, 20J | 10.6 | 13.3 |
| | H-SL24 | SOL 24, 24J | 10.6 | 15.9 |
| | H-SL28 | SOL 28 | 10.6 | 18.4 |
| | H-SL44 | SOL 44 | 16 | 27.9 |
| | H-SOJ32 | SOJ 32 | 13.5 | 20.6 |
| | H-SOJ40 | SOJ 40 | 13.5 | 25.4 |
| | H-TS24 | 20-24 PIN TSOP | 17 | 7.1 |
| | H-TS32 | 28-32 PIN TSOP | 21 | 9.1 |
| | H-TS40 | 40 PIN TSOP | 21 | 10.8 |
| | H-TS48 | 48 PIN TSOP | 21 | 13.3 |
| | H-TSW24 | 20-24 PIN TSOP | 10.2 | 18.4 |
| | H-TSW44 | 24-28/40-44 PIN TSOP | 12.7 | 19.8 |

| Outline: Nozzles for PLCC, BQFP, QFP Packages | Part Number | Chip Package | Dimension A | Dimension B |
|---|-------------|------------------------|-------------|-------------|
|  | H-P20 | PLCC-20 | 11.9 | 11.9 |
| | H-P28 | PLCC-28 | 14.5 | 14.5 |
| | H-P32 | PLCC-32 | 16.9 | 14.3 |
| | H-P44 | PLCC-44 | 19.5 | 19.5 |
| | H-P52 | PLCC-52 | 22 | 22.1 |
| | H-P68 | PLCC-68 | 27 | 27.2 |
| | H-P84 | PLCC-84 | 32.4 | 32.4 |
| | H-Q07 | QFP-48 | 8.4 | 8.4 |
| | H-Q10 | QFP-44 | 13.4 | 13.4 |
| | H-Q14 | QFP-52, 80 | 17.3 | 17.3 |
| | H-Q1420 | QFP-64, 80, 100 | 23.4 | 18.1 |
| | H-Q28 | QFP-120, 128, 144, 160 | 31.2 | 31.2 |
| | H-BQ23 | BQFP-100 | 22.4 | 22.4 |
| | H-Q3232 | QFP-240 | 34.5 | 34.5 |
| | H-BQ38 | BQFP-196 | 37.7 | 37.7 |
| | H-Q2626 | QFP-304 | 29.8 | 29.8 |